

# HiPerFRED

$$V_{RRM} = 300V$$

$$I_{FAV} = 2x \ 30A$$

$$t_{rr} = 30ns$$

High Performance Fast Recovery Diode  
 Low Loss and Soft Recovery  
 Parallel legs

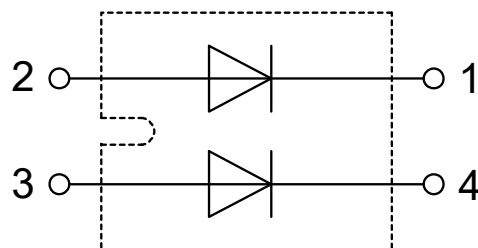
Part number

**DSEP2x31-03A**



Backside: isolated

 E72873



### Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low  $I_{rm}$ -values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low  $I_{rm}$  reduces:
  - Power dissipation within the diode
  - Turn-on loss in the commutating switch

### Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

### Package: SOT-227B (minibloc)

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate: Copper internally DCB isolated
- Advanced power cycling

### Disclaimer Notice

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Fast Diode				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
$V_{RSM}$	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}C$			300	V	
$V_{RRM}$	max. repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}C$			300	V	
$I_R$	reverse current, drain current	$V_R = 300 V$	$T_{VJ} = 25^{\circ}C$		10	$\mu A$	
		$V_R = 300 V$	$T_{VJ} = 150^{\circ}C$		1	mA	
$V_F$	forward voltage drop	$I_F = 30 A$	$T_{VJ} = 25^{\circ}C$		1,23	V	
		$I_F = 60 A$			1,40	V	
		$I_F = 30 A$	$T_{VJ} = 150^{\circ}C$		0,90	V	
		$I_F = 60 A$			1,10	V	
$I_{FAV}$	average forward current	$T_C = 105^{\circ}C$ rectangular $d = 0.5$	$T_{VJ} = 150^{\circ}C$		30	A	
$V_{FO}$	threshold voltage	} for power loss calculation only	$T_{VJ} = 150^{\circ}C$		0,71	V	
$r_F$	slope resistance				6,2	m $\Omega$	
$R_{thJC}$	thermal resistance junction to case				1,15	K/W	
$R_{thCH}$	thermal resistance case to heatsink			0,1		K/W	
$P_{tot}$	total power dissipation		$T_C = 25^{\circ}C$		100	W	
$I_{FSM}$	max. forward surge current	$t = 10 ms; (50 Hz), sine; V_R = 0 V$	$T_{VJ} = 45^{\circ}C$		300	A	
$C_J$	junction capacitance	$V_R = 150 V$ $f = 1 MHz$	$T_{VJ} = 25^{\circ}C$		66	pF	
$I_{RM}$	max. reverse recovery current	} $I_F = 30 A; V_R = 150 V$	$T_{VJ} = 25^{\circ}C$		10	A	
			$T_{VJ} = 100^{\circ}C$		12,5	A	
$t_{rr}$	reverse recovery time	} $-di_F/dt = 400 A/\mu s$	$T_{VJ} = 25^{\circ}C$		30	ns	
			$T_{VJ} = 100^{\circ}C$		55	ns	



Package SOT-227B (minibloc)		Ratings				
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$I_{RMS}$	RMS current	per terminal			100	A
$T_{VJ}$	virtual junction temperature		-40		150	°C
$T_{op}$	operation temperature		-40		125	°C
$T_{stg}$	storage temperature		-40		150	°C
<b>Weight</b>				30		g
$M_D$	mounting torque		1,1		1,5	Nm
$M_T$	terminal torque		1,1		1,5	Nm
$d_{Spp/App}$	creepage distance on surface   striking distance through air	terminal to terminal	10,5	3,2		mm
$d_{Spb/Apb}$		terminal to backside	8,6	6,8		mm
$V_{ISOL}$	isolation voltage	t = 1 second			3000	V
		t = 1 minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA		2500	V

**Product Marking**

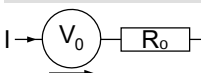


Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSEP2x31-03A	DSEP2x31-03A	Tube	10	473278

**Equivalent Circuits for Simulation**

\* on die level

$T_{VJ} = 150^{\circ}C$

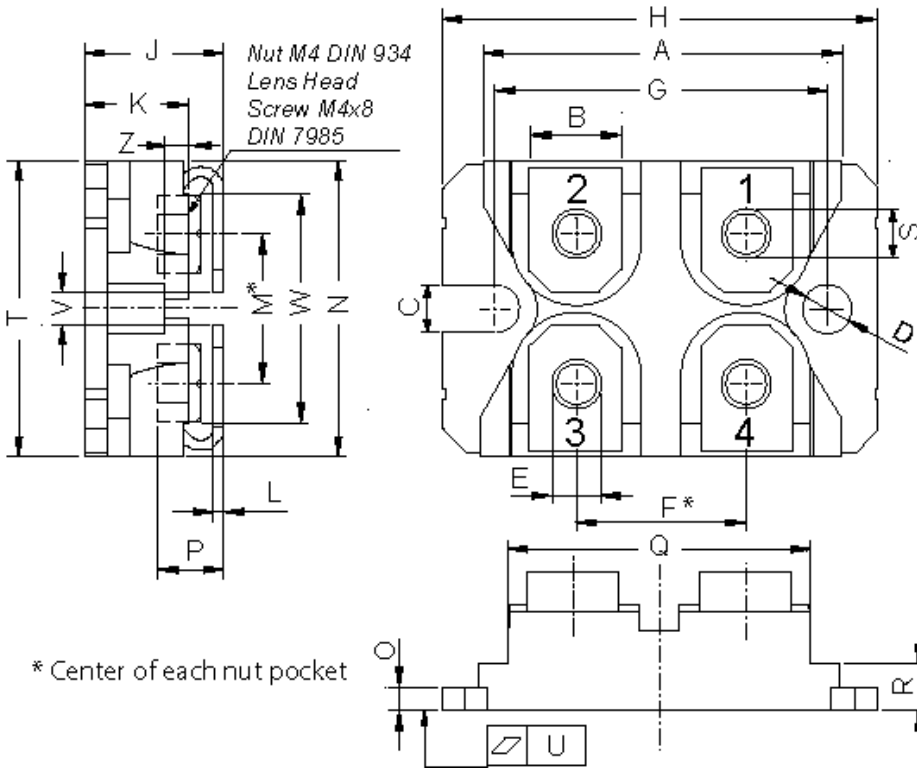


**Fast Diode**

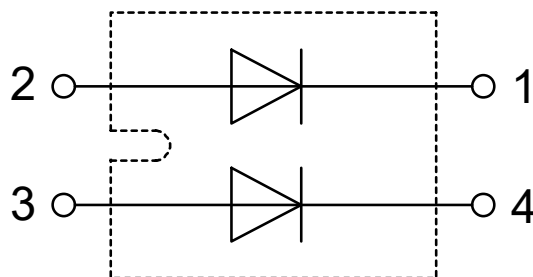
$V_{0\ max}$	threshold voltage	0,71	V
$R_{0\ max}$	slope resistance *	4,3	mΩ



**Outlines SOT-227B (minibloc)**



Dim.	Millimeter		Inches	
	min	max	min	max
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	37.80	38.23	1.488	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.74	0.84	0.029	0.033
M	12.50	13.10	0.492	0.516
N	25.15	25.42	0.990	1.001
O	1.95	2.13	0.077	0.084
P	4.95	6.20	0.195	0.244
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.167
S	4.55	4.85	0.179	0.191
T	24.59	25.25	0.968	0.994
U	-0.05	0.10	-0.002	0.004
V	3.20	5.50	0.126	0.217
W	19.81	21.08	0.780	0.830
Z	2.50	2.70	0.098	0.106



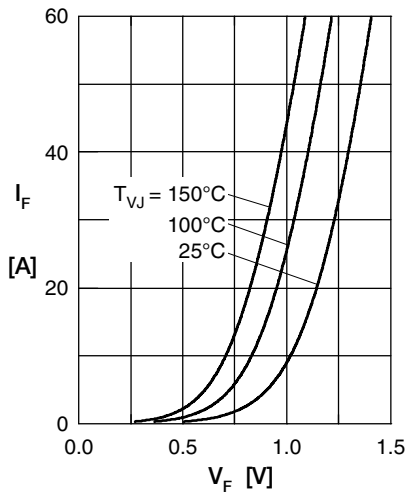
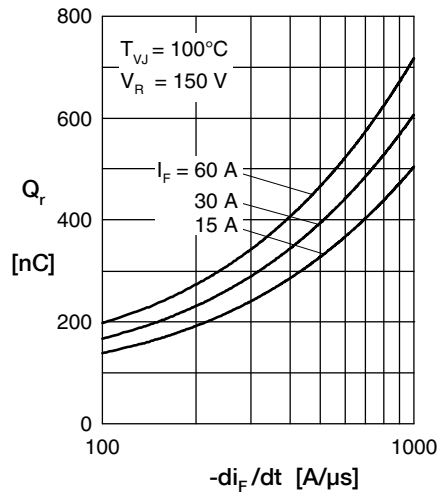
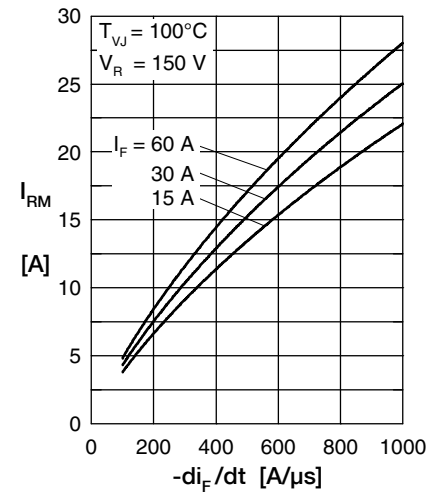
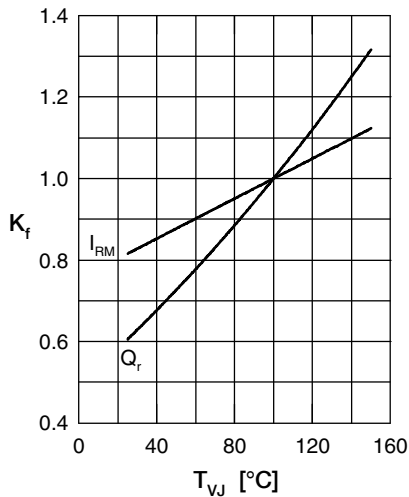
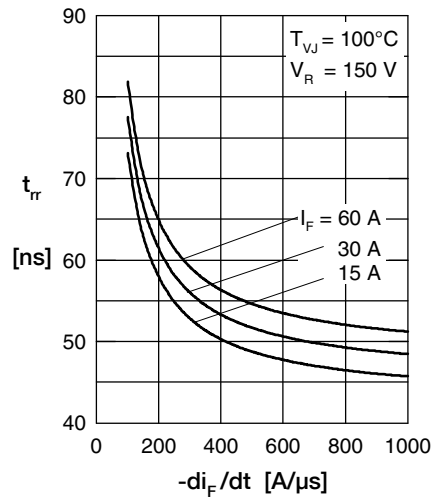
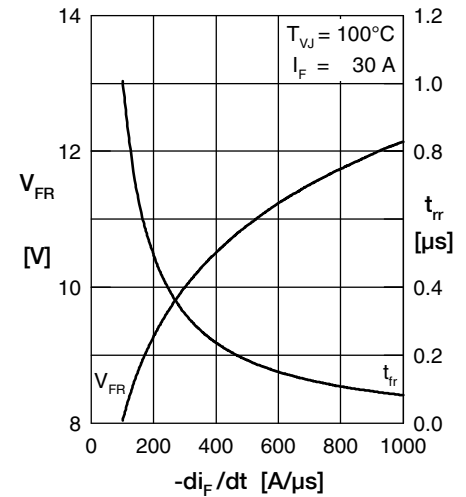
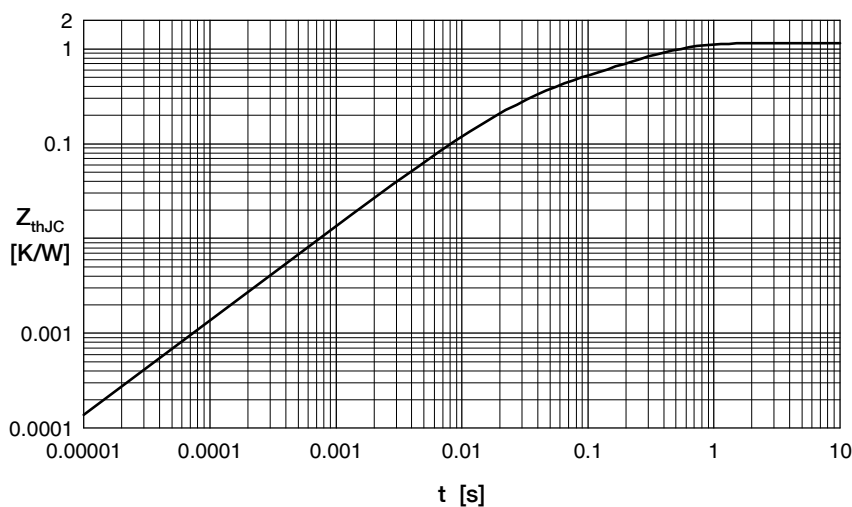
**Fast Diode**

 Fig. 1 Forward current  $I_F$  versus  $V_F$ 

 Fig. 2 Typ. reverse recovery charge  $Q_r$  versus  $-di_F/dt$ 

 Fig. 3 Typ. peak reverse current  $I_{RM}$  versus  $-di_F/dt$ 

 Fig. 4 Typ. dynamic parameters  $Q_r$ ,  $I_{RM}$  versus  $T_{VJ}$ 

 Fig. 5 Typ. recovery time  $t_{tr}$  versus  $-di_F/dt$ 

 Fig. 6 Typ. peak forward voltage  $V_{FR}$  and  $t_{tr}$  versus  $di_F/dt$ 


Fig. 7 Transient thermal resistance junction to case

 Constants for  $Z_{thJC}$  calculation ...A:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.465	0.0052
2	0.179	0.0003
3	0.256	0.0397

 Constants for  $Z_{thJC}$  calculation ...AR:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.368	0.0052
2	0.1417	0.0003
3	0.0295	0.0004
4	0.5604	0.0092